



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C64M16MD2A-25BIN								
Part Weight:		181.449mg								
NO.	Material	Type	Component wt (mg)	Substances	Purpose	CAS No.	Element wt (%)	Weight (mg)	wt % of Total unit wt	PPM
1	Molding Compound	G760LB	105.676	Epoxy Resin	Resin	Trade Secret	8.00%	8.454	4.6592%	46,592
				Phenol Resin A	Resin	Trade Secret	3.00%	3.170	1.7472%	17,472
				Phenol Resin B	Resin	Trade Secret	3.00%	3.170	1.7472%	17,472
				Silica(Amorphous) A	Base material	60676-86-0	75.00%	79.257	43.6800%	436,800
				Silica(Amorphous) B	Base material	7631-86-9	2.50%	2.642	1.4560%	14,560
				Metal Hydroxide	Base material	Trade Secret	8.00%	8.454	4.6592%	46,592
				Carbon Black	Additive	1333-86-4	0.50%	0.528	0.2912%	2,912
2	Substrate	BT	52.348				100.00%	52.348	28.8500%	288,500
3	DAF	EM760	1.343	Acrylic resin	Base material	Trade Secret	50.00%	0.672	0.3701%	3,701
				Silica, amorphous	Base material	7631-86-9	45.00%	0.604	0.3331%	3,331
				Phenol resin	Base material	Trade Secret	5.00%	0.067	0.0370%	370
4	Wire	Au 0.8mil	0.962	GOLD	Base material	7440-57-5	99.9992%	0.962	0.5302%	5,302
				Beryllium	Base material	7440-41-7	0.0008%	0.000	0.0000%	0
5	Solder Ball	M705	12.937	Tin (Sn)	Plating material	7440-31-5	96.50%	12.484	6.8803%	68,803
				Ag	Plating material	7440-22-4	3.00%	0.388	0.2139%	2,139
				Cu	Plating material	7440-50-8	0.50%	0.065	0.0356%	356
6	Die		8.183	Si	Chip	7440-21-3	100.00%	8.183	4.5098%	45,098
								181.449	100.0000%	1,000,000

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 Alliance Memory Inc. reserves the right to change products or specification without notice.